



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Klein L. Johnson                      Examiner: Mooney, Michael P.  
Serial No.: 09/342,801                      Group Art Unit: 2877  
Filed: June 29, 1999  
For: HERMETIC CHIP-SCALE PACKAGE FOR PHOTONIC DEVICE  
Docket No.: H16-25073 US (1139.1125101)

**INFORMATION DISCLOSURE STATEMENT (37 C.F.R. §1.97(b))**

**Mail Stop RCE**

Assistant Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATE UNDER 37 C.F.R. 1.10:** The undersigned hereby certifies that this paper or papers, as described herein, are being deposited in the United States Postal Service, "Express Mail Post Office to Addressee" having an Express Mail mailing label number of: EV315608966US, in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450, on this 3rd day of October, 2003.

By \_\_\_\_\_

*Lynn Thompson*  
Lynn Thompson

Dear Sir:

With regard to the above-identified application, the items of information listed on the enclosed Form 1449 are brought to the attention of the Examiner.

This statement should be considered because it is submitted before the mailing date of a first Office Action on-the-merits. Accordingly, no fee is due for consideration of the items listed on the enclosed Form 1449.

In accordance with 37 C.F. R. §1.98(a)(2), a copy of each document or other information listed on the enclosed Form 1449 is provided.

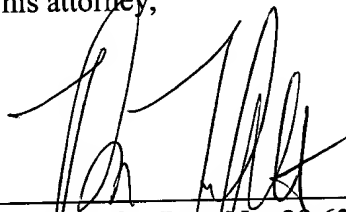
No representation is intended to be made hereby that any of the cited references establishes, by itself or in combination with other information, a prima facie case of unpatentability of any claim of the present case.

Consideration of the items listed is respectfully requested. Pursuant to the provisions of M.P.E.P. 609, it is requested the Examiner return a copy of the attached Form 1449, marked as being considered and initialed by the Examiner, to the undersigned with the next official communication.

Respectfully submitted,

Klein L. Johnson

By his attorney,



Dated: October 3, 2003

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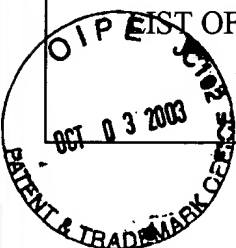
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OFFICE OF PATENTS AND PUBLICATIONS FOR  
APPLICANT'S INFORMATION  
DISCLOSURE STATEMENT

## U.S. PATENT DOCUMENTS

Examiner Initial	Document No.	Date	Name	Class	Sub Class	Filing Date If Appropriate
	4,873,566	10/10/1989	Hokanson et al.			
	4,897,711	01/30/1990	Blonder et al.			
	5,052,009	09/24/1991	Tsubol et al.			
	5,089,861	02/18/1992	Tanaka et al.			
	5,748,658	05/05/1998	Nakanishi et al.			
	5,763,888	06/09/1998	Glasheen et al.			
	5,812,717	09/22/1998	Gilliland			
	5,835,514	11/10/1998	Yuen et al.			
	6,081,638	06/27/2000	Zhou			
	6,194,789	02/27/2001	Zhou			
	6,205,274	03/20/2001	Zhou			
	6,275,513	08/14/2001	Chnag-Hasnain et al.			
	6,521,989	02/18/2003	Zhou			
	6,588,949	07/08/2003	Zhou			

## FOREIGN PATENT DOCUMENTS

Examiner Initial	Document No.	Date	Country	Translation Yes No

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	Alles, David S., "Trends in Laser Packaging," IEEE, 0569-5503/90/0000-0185, pp. 185-192.
	Fukuoka, et al., "Hybrid Microcircuit Fiber Optics System Receiver Hermetically Sealed," The International Journal for Hybrid Microelectronics, vol. 6, no. 2, pp. 5-9, December 1983.
	Kosaka, et al., "Plastic-Based Receptacle-Type VCSEL-Array Modules with One and Two Dimensions Fabricated Using the Self-Alignment Mounting Technique," IEEE, Electronic

## FORM PTO-1449

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LIST OF PATENTS AND PUBLICATIONS FOR  
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Components and Technology Conference, pp. 382-390, 1997.

Norton, et al., "OTPOBUS<sup>TM</sup> I: A Production Parallel Fiber Optical Interconnect," IEEE,  
Electronic Components and Technology Conference, pp. 204-209, 1997.Spector, Murray, "Design of a Solid State Laser Hybrid Package," International Journal for Hybrid  
Microelectronics, vol. 5, no. 2, pp. 172-174, November 1982.

EXAMINER:

DATE CONSIDERED:

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.